

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
20V	50mΩ@4.5V	3A
	70mΩ@2.5V	

Feature

- Advanced trench technology
- Excellent $R_{DS(ON)}$
- Low gate charge

Application

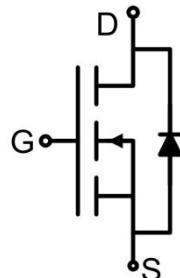
- Battery protection
- Load Switch
- Uninterruptible power supply

Package

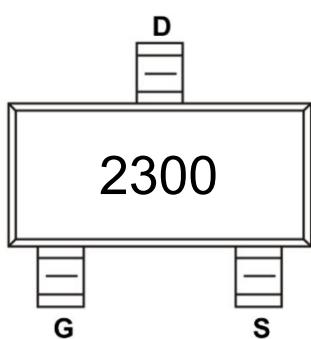


SOT-23

Circuit diagram



Marking



Absolute maximum ratings (T_c=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current ¹⁾ (V _{GS} =4.5V, T _A =25°C)	I _D	3	A
Pulsed Drain Current ²⁾	I _{DM}	7.4	A
Power Dissipation ³⁾ (T _A =25°C)	P _D	0.9	W
Thermal Resistance from Junction to Ambient ¹⁾	R _{θJA}	125	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_J=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	20			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	0.4	0.6	1.2	V
Drain-source on-resistance ²⁾	R _{DS(on)}	V _{GS} = 4.5V, I _D = 2A		42	50	mΩ
		V _{GS} = 2.5V, I _D = 1.5A		54	70	
Dynamic characteristics⁴⁾						
Input Capacitance	C _{iss}	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz		184		pF
Output Capacitance	C _{oss}			38		
Reverse Transfer Capacitance	C _{rss}			28		
Total Gate Charge	Q _g	V _{DS} = 10V, V _{GS} = 4.5V, I _D = 3A		2.7		nC
Gate-Source Charge	Q _{gs}			0.4		
Gate-Drain Charge	Q _{gd}			0.5		
Turn-on delay time	t _{d(on)}	V _{DS} = 10V, V _{GS} = 4.5V, R _{GEN} = 3Ω, I _D = 3A		2.3		nS
Turn-on rise time	t _r			3.1		
Turn-off delay time	t _{d(off)}			9.2		
Turn-off fall time	t _f			2.5		
Source-Drain Diode characteristics						
Diode Forward Current	I _S				3	A
Diode Forward voltage	V _{SD}	V _{GS} = 0V, I _S = 3A			1.2	V

Notes:

- 1) The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2) The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
- 3) The power dissipation is limited by 150°C junction temperature.
- 4) Guaranteed by design, not subject to production testing.

Typical Characteristics

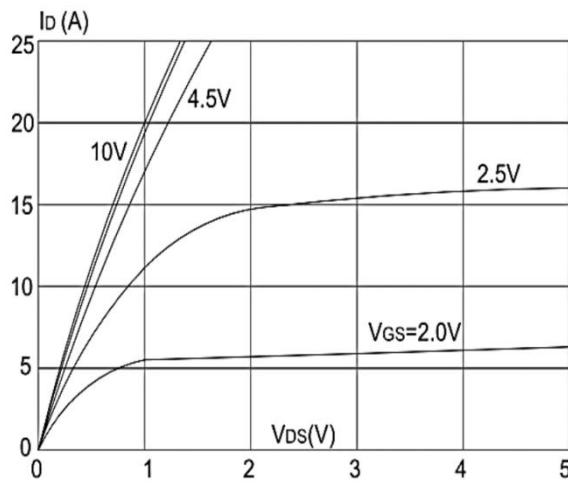


Figure 1: Output Characteristics

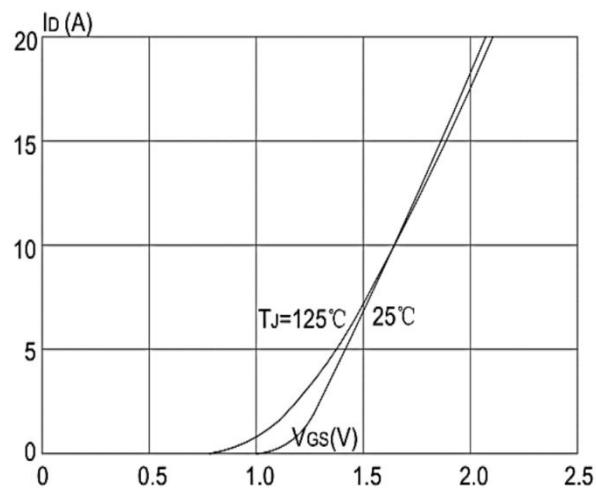


Figure 2: Typical Transfer Characteristics

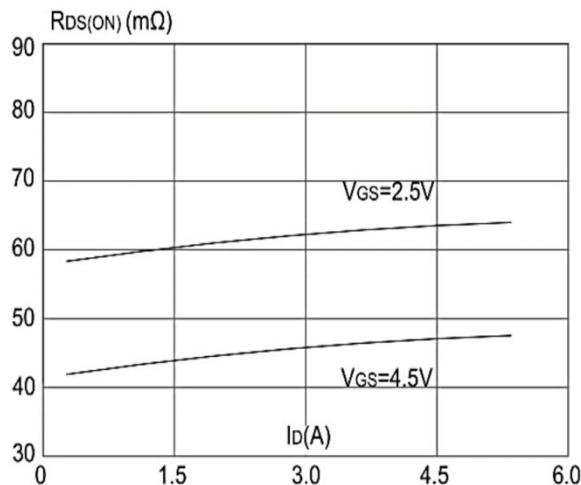


Figure 3: On-resistance vs. Drain Current

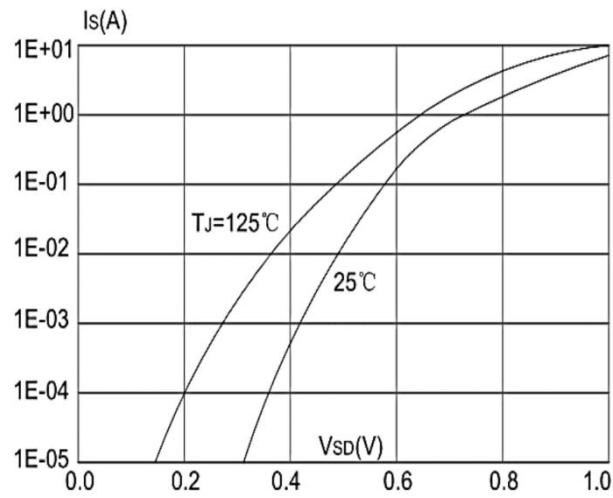


Figure 4: Body Diode Characteristics

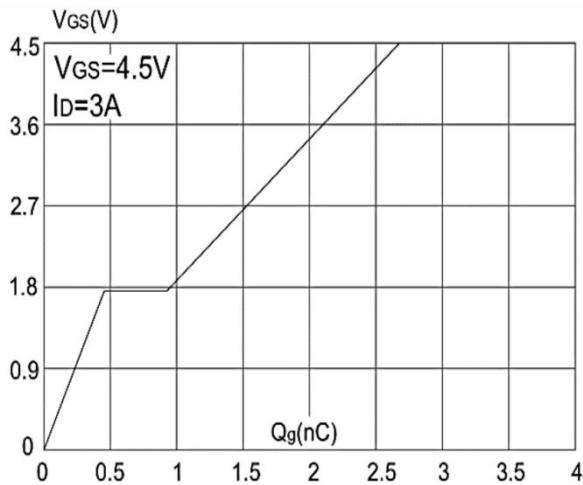


Figure 5: Gate Charge Characteristics

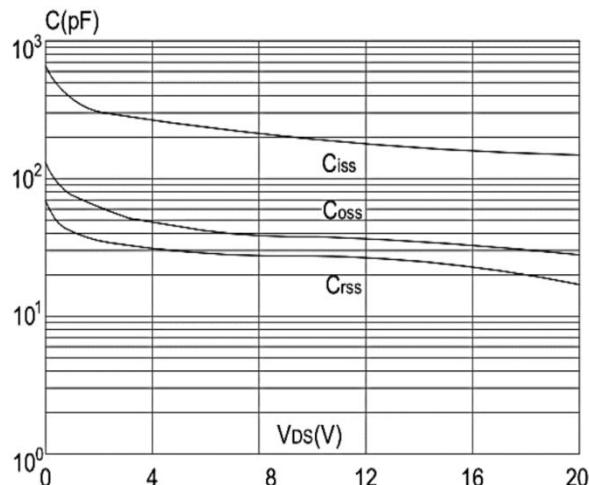


Figure 6: Capacitance Characteristics

Typical Characteristics

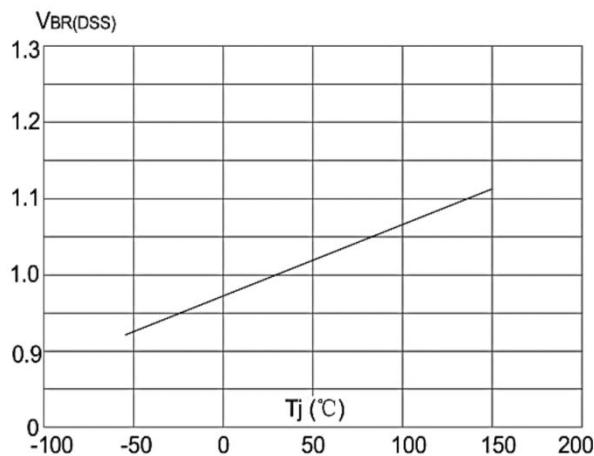


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

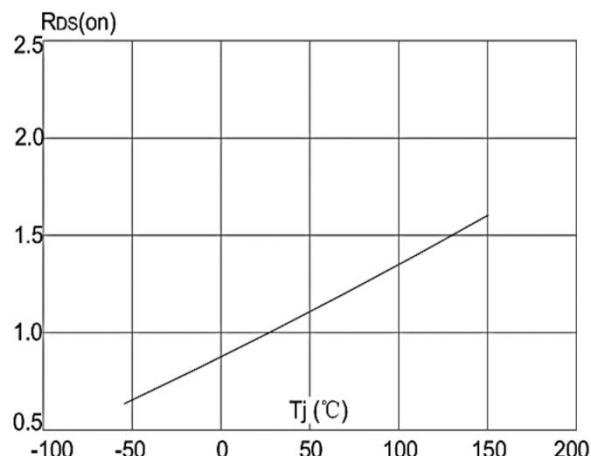


Figure 8: Normalized on Resistance vs. Junction Temperature

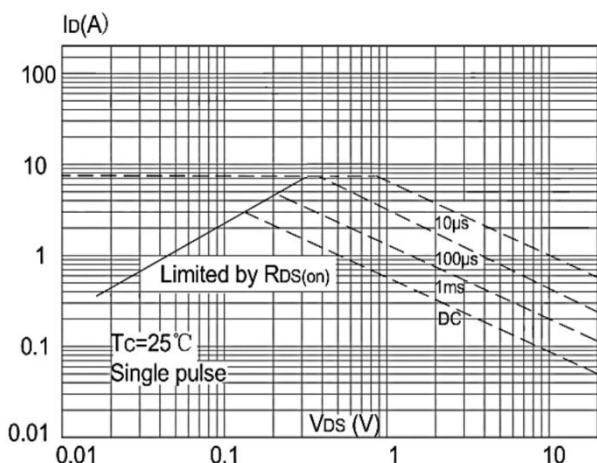


Figure 9: Maximum Safe Operating Area

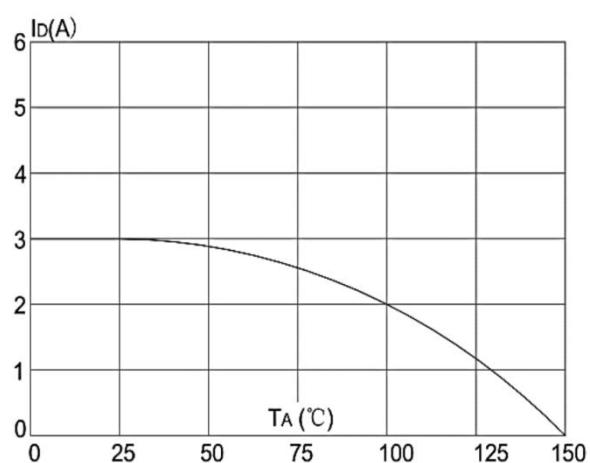


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

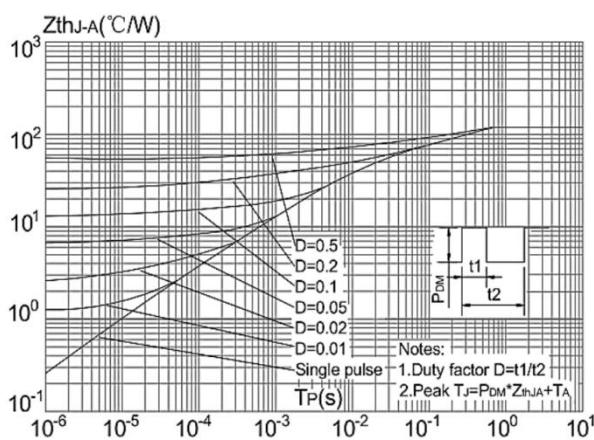
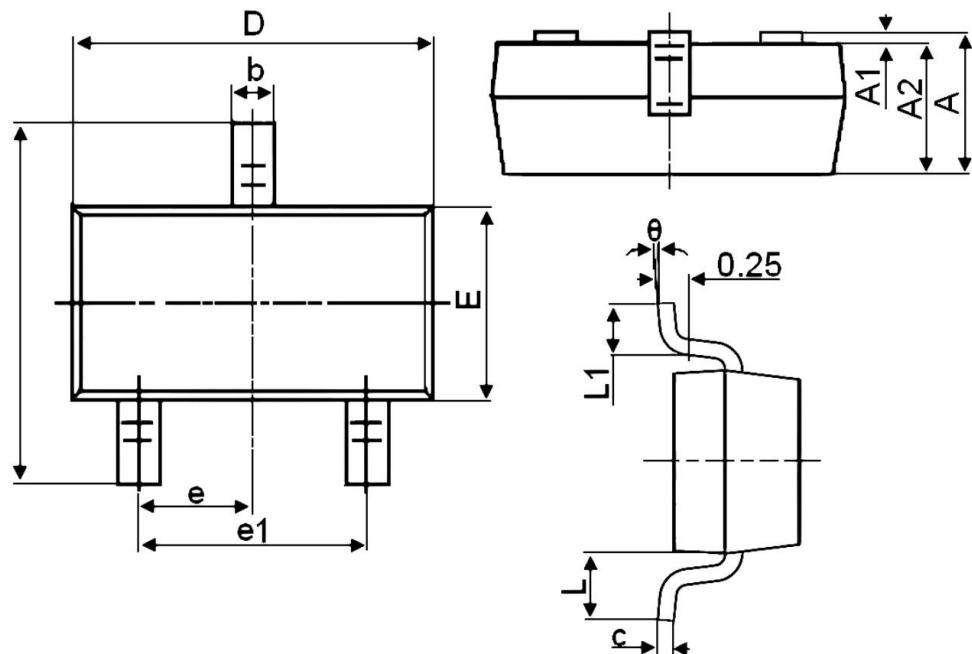


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 REF.		0.037 REF.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°